



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-02-11
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L5962TR	M92S*UH89BC6	A	MU1A	2014-02-11
	Amount	UoM	Unit type	ST ECOPACK Grade
	1978.10	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	11x15.7x3.14	36	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	true
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	M92S*UH89BC6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	18.387	mg	supplier	die	Silicon (Si)	7440-21-3		17.587	mg	956491	8891
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.132	mg	7179	67
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.132	mg	7179	67
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.015	mg	816	8
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.028	mg	1523	14
die (s)				supplier	passivation	Indium Tin oxide (In2O3.SnO2)	50926-11-9		0.355	mg	19307	179
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.010	mg	544	5
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.027	mg	1468	14
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.090	mg	4895	45
die (s)				supplier	polymer die coating	Polymer resist (Black resist)	Proprietary		0.011	mg	598	6
Leadframe	Copper & its alloys	1268.131	mg	supplier	alloy	Copper (Cu)	7440-50-8		1263.205	mg	996116	638595
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.582	mg	459	294
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		1.062	mg	837	537
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		3.282	mg	2588	1659
Die attach		10.971	mg	JIG Table A	glue or tape	Lead (Pb)	7439-92-1	7a-Lead in high me	10.696	mg	974934	5407
Die attach				supplier	glue or tape	Silver (Ag)	7440-22-4		0.165	mg	15040	83
Die attach				supplier	glue or tape	Tin (Sn)	7440-31-5		0.110	mg	10026	56
Bonding wire		1.711		supplier	wire	Gold (Au)	7440-57-5		0.737	mg	430742	373
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		0.971	mg	567504	491
Bonding wire				supplier	wire	Palladium (Pd)	7440-05-3		0.002	mg	1169	1
Bonding wire				supplier	wire	Platinum (Pt)	7440-06-4		0.001	mg	584	1
encapsulation		669.007	mg	supplier	mold compound	Phenol Resin	205830-20-2		26.761	mg	40001	13529
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		20.070	mg	30000	10146
encapsulation				supplier	mold compound	epoxy resin	na		20.070	mg	30000	10146
encapsulation				supplier	mold compound	carbon black	1333-86-4		1.338	mg	2000	676
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		600.768	mg	898000	303710
connections coating	Solder	9.893	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		9.893	mg	1000000	5001